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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	418
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Through Hole
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	624-BCCGA
Supplier Device Package	624-CCGA (32.5x32.5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-cgs624m

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

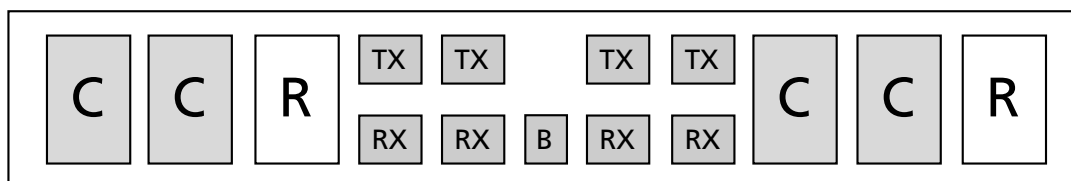


Figure 1-4 • AX SuperCluster

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

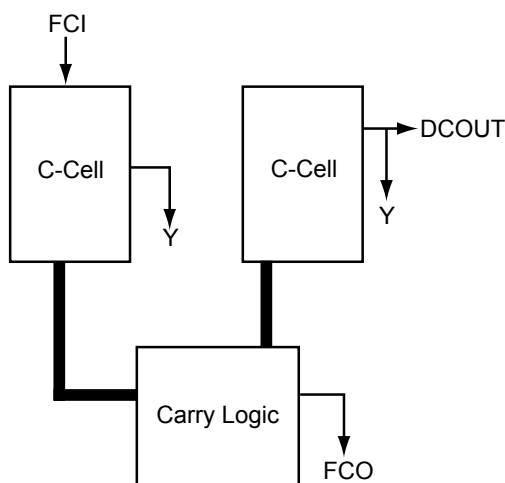


Figure 1-5 • AX 2-Bit Carry Logic

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • Number of Core Tiles per Device

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

Up to four individual signals can be brought out to dedicated probe pins (PRA/B/C/D) on the device. The probe circuitry is accessed and controlled via Silicon Explorer II, Microsemi's integrated verification and logic analysis tool that attaches to the serial port of a PC and communicates with the FPGA via the JTAG port (See "Silicon Explorer II Probe Interface" on page 2-109).

Summary

Microsemi's Axcelerator family of FPGAs extends the successful SX-A architecture, adding embedded RAM/FIFOs, PLLs, and high-speed I/Os. With the support of a suite of robust software tools, design engineers can incorporate high gate counts and fixed pins into an Axcelerator design yet still achieve high performance and efficient device utilization.

Related Documents

Application Notes

Simultaneous Switching Noise and Signal Integrity

http://www.microsemi.com/soc/documents/SSN_AN.pdf

Axcelerator Family PLL and Clock Management

http://www.microsemi.com/soc/documents/AX_PLL_AN.pdf

Implementation of Security in Actel Antifuse FPGAs

http://www.microsemi.com/soc/documents/Antifuse_Security_AN.pdf

User's Guides and Manuals

Antifuse Macro Library Guide

http://www.microsemi.com/soc/documents/libguide_UG.pdf

SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder

http://www.microsemi.com/soc/documents/genguide_ug.pdf

Silicon Sculptor II User's Guide

http://www.microsemi.com/soc/documents/silisculptII_sculpt3_ug.pdf

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Understanding Actel Antifuse Device Security

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Miscellaneous

Libero IDE flow diagram

<http://www.microsemi.com/soc/products/tools/libero/flow.html>

3.3 V LVTTTL

Low-Voltage Transistor-Transistor Logic is a general purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTTL input buffer and push-pull output buffer.

Table 2-20 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
−0.3	0.8	2.0	3.6	0.4	2.4	24	−24

AC Loadings

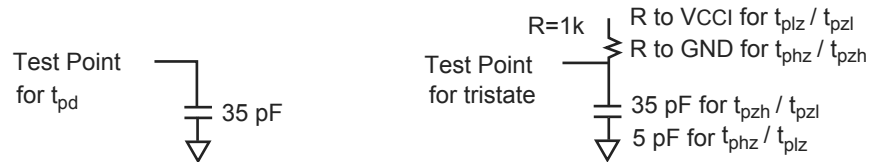


Figure 2-15 • AC Test Loads

Table 2-21 • AC Waveforms, Measuring Points, and Capacitive Load

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
0	3.0	1.40	N/A	35

Note: * Measuring Point = VTRIP

Timing Characteristics

Table 2-22 • 3.3 V LVTTL I/O Module

Worst-Case Commercial Conditions $V_{CCA} = 1.425\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTL Output Drive Strength = 1 (8 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		14.28		16.27		19.13	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		15.25		17.37		20.42	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		14.26		16.24		19.09	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.56		1.57		1.58	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		1.95		1.96		1.97	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

2.5 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-23 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	0.7	1.7	3.6	0.4	2.0	12	-12

AC Loadings

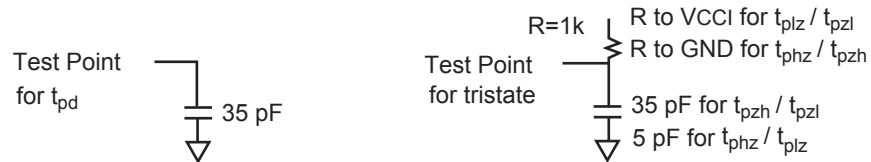


Figure 2-16 • AC Test Loads

Table 2-24 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
0	2.5	1.25	N/A	35

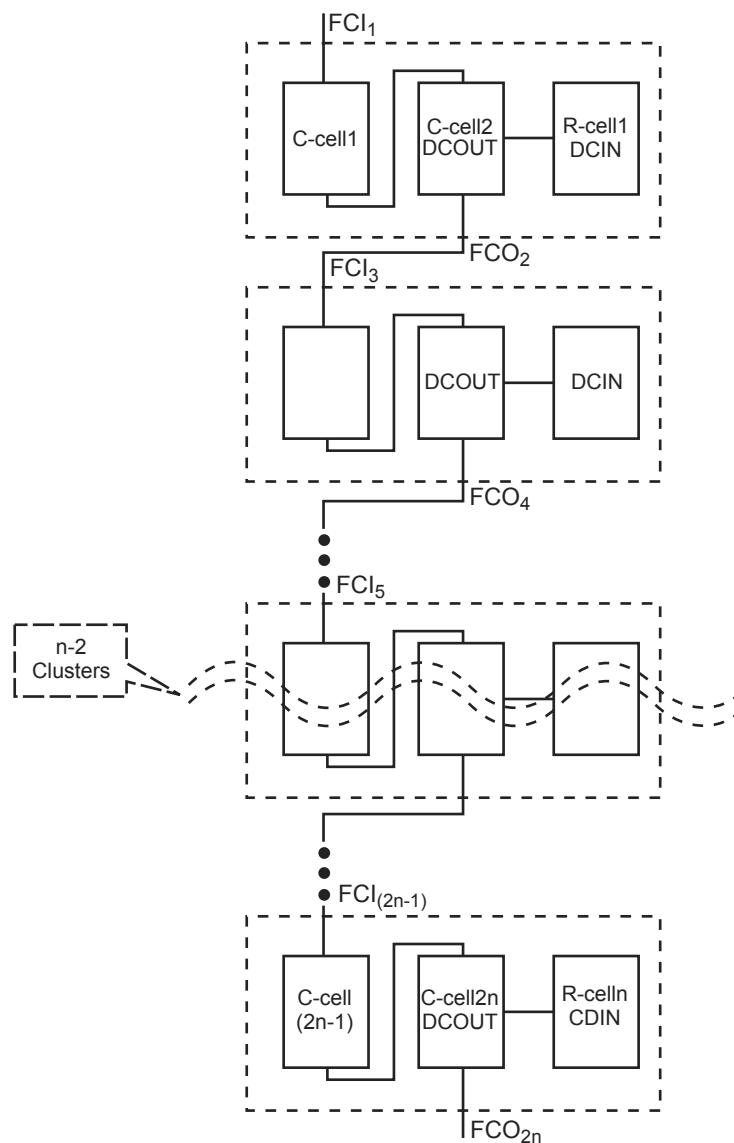
Note: * Measuring Point = VTRIP

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVCMOS15 (JESD8-11) I/O Module Timing								
t _{DP}	Input Buffer		3.59		4.09		4.81	ns
t _{PY}	Output Buffer		6.05		6.89		8.10	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns



Note: The carry-chain sequence can end on either C-cell.

Figure 2-30 • Carry-Chain Sequencing of C-Cells

Timing Characteristics

Refer to Table 2-62 on page 2-55 for more information on carry-chain timing.

R-Cell

Introduction

The R-cell, the sequential logic resource of the Axcelerator devices, is the second logic module type in the AX family architecture. It includes clock inputs for all eight global resources of the Axcelerator architecture as well as global presets and clears (Figure 2-31).

The main features of the R-cell include the following:

- Direct connection to the adjacent logic module through the hardwired connection DCIN. DCIN is driven by the DCOUT of an adjacent C-cell via the Direct-Connect routing resource, providing a connection with less than 0.1 ns of routing delay.
- The R-cell can be used as a standalone flip-flop. It can be driven by any C-cell or I/O modules through the regular routing structure (using DIN as a routable data input). This gives the option of using the R-Cell as a 2:1 MUXed flip-flop as well.
- Provision of data enable-input (S0).
- Independent active-low asynchronous clear (CLR).
- Independent active-low asynchronous preset (PSET). If both CLR and PSET are low, CLR has higher priority.
- Clock can be driven by any of the following (CKP selects clock polarity):
 - One of the four high performance hardwired fast clocks (HCLKs)
 - One of the four routed clocks (CLKs)
 - User signals
- Global power-on clear (GCLR) and preset (GPSET), which drive each flip-flop on a chip-wide basis.
 - When the Global Set Fuse option in the Designer software is unchecked (by default), GCLR = 0 and GPSET = 1 at device power-up. When the option is checked, GCLR = 1 and GPSET = 0. Both pins are pulled High when the device is in user mode. Refer to the "Simulation Support for GCLR/GPSET in Axcelerator" section of the *Antifuse Macro Library Guide* for information on simulation support for GCLR and GPSET.
- S0, S1, PSET, and CLR can be driven by routed clocks CLKE/F/G/H or user signals.
- DIN and S1 can be driven by user signals.

As with the C-cell, the configuration of the R-cell to perform various functions is handled automatically for the user through Microsemi's extensive macro library (see the *Antifuse Macro Library Guide* for a complete listing of available AX macros).

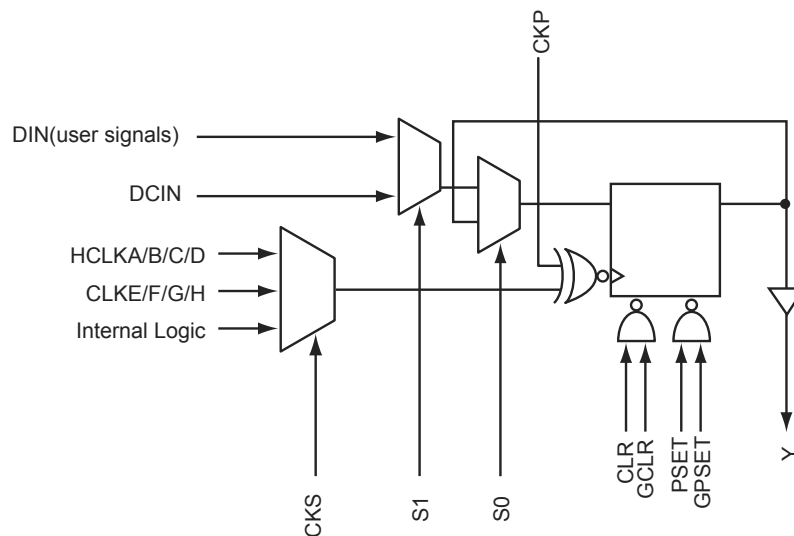


Figure 2-31 • R-Cell

Timing Characteristics

Table 2-65 • AX125 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		-2 Speed	-1 Speed	Std Speed	Units
Parameter	Description	Typical	Typical	Typical	
Predicted Routing Delays					
t _{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t _{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t _{RD1}	Routing delay for FO1	0.35	0.40	0.47	ns
t _{RD2}	Routing delay for FO2	0.38	0.43	0.51	ns
t _{RD3}	Routing delay for FO3	0.43	0.48	0.57	ns
t _{RD4}	Routing delay for FO4	0.48	0.55	0.64	ns
t _{RD5}	Routing delay for FO5	0.55	0.62	0.73	ns
t _{RD6}	Routing delay for FO6	0.64	0.72	0.85	ns
t _{RD7}	Routing delay for FO7	0.79	0.89	1.05	ns
t _{RD8}	Routing delay for FO8	0.88	0.99	1.17	ns
t _{RD16}	Routing delay for FO16	1.49	1.69	1.99	ns
t _{RD32}	Routing delay for FO32	2.32	2.63	3.10	ns

Table 2-66 • AX250 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		-2 Speed	-1 Speed	Std Speed	Units
Parameter	Description	Typical	Typical	Typical	
Predicted Routing Delays					
t _{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t _{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t _{RD1}	Routing delay for FO1	0.39	0.45	0.53	ns
t _{RD2}	Routing delay for FO2	0.41	0.46	0.54	ns
t _{RD3}	Routing delay for FO3	0.48	0.55	0.64	ns
t _{RD4}	Routing delay for FO4	0.56	0.63	0.75	ns
t _{RD5}	Routing delay for FO5	0.60	0.68	0.80	ns
t _{RD6}	Routing delay for FO6	0.84	0.96	1.13	ns
t _{RD7}	Routing delay for FO7	0.90	1.02	1.20	ns
t _{RD8}	Routing delay for FO8	1.00	1.13	1.33	ns
t _{RD16}	Routing delay for FO16	2.17	2.46	2.89	ns
t _{RD32}	Routing delay for FO32	3.55	4.03	4.74	ns

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

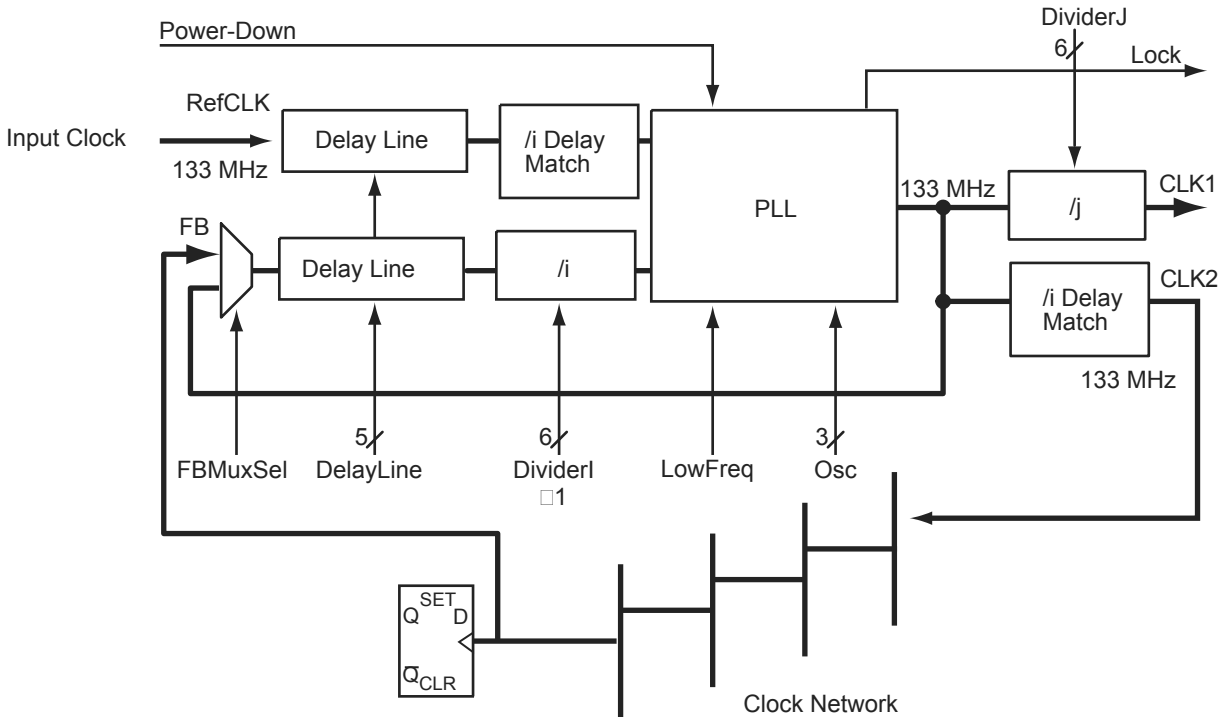


Figure 2-56 • Using the PLL for Clock Deskewing

Embedded Memory

The AX architecture provides extensive, high-speed memory resources to the user. Each 4,608 bit block of RAM contains its own embedded FIFO controller, allowing the user to configure each block as either RAM or FIFO.

To meet the needs of high performance designs, the memory blocks operate in synchronous mode for both read and write operations. However, the read and write clocks are completely independent, and each may operate up to and above 500 MHz.

No additional core logic resources are required to cascade the address and data buses when cascading different RAM blocks. Dedicated routing runs along each column of RAM to facilitate cascading.

The AX memory block includes dedicated FIFO control logic to generate internal addresses and external flag logic (FULL, EMPTY, AFULL, AEMPTY). Since read and write operations can occur asynchronously to one another, special control circuitry is included to prevent metastability, overflow, and underflow. A block diagram of the memory module is illustrated in Figure 2-57.

During RAM operation, read (RA) and write (WA) addresses are sourced by user logic and the FIFO controller is ignored. In FIFO mode, the internal addresses are generated by the FIFO controller and routed to the RAM array by internal MUXes. Enables with programmable polarity are provided to create upper address bits for cascading up to 16 memory blocks. When cascading memory blocks, the bussed signals WA, WD, WEN, RA, RD, and REN are internally linked to eliminate external routing congestion.

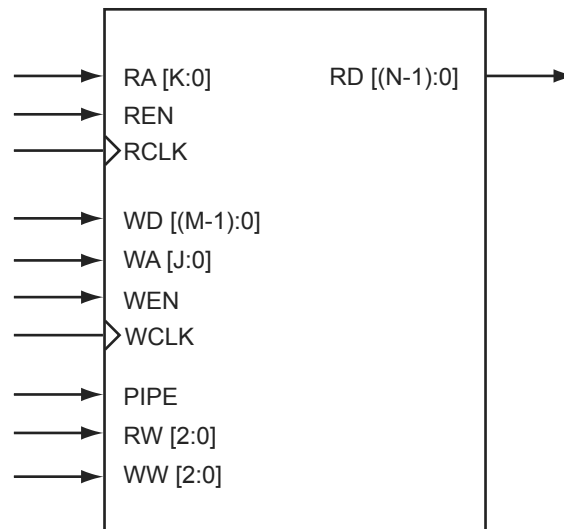


Figure 2-57 • Axcelerator Memory Module

Table 2-98 • One FIFO Block

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
FIFO Module Timing								
t _{WSU}	Write Setup		11.40		12.98		15.26	ns
t _{WHD}	Write Hold		0.22		0.25		0.30	ns
t _{WCKH}	WCLK High		0.75		0.75		0.75	ns
t _{WCKL}	WCLK Low		0.88		0.88		0.88	ns
t _{WCKP}	Minimum WCLK Period	1.63		1.63		1.63		ns
t _{RSU}	Read Setup		11.63		13.25		15.58	ns
t _{RHD}	Read Hold		0.00		0.00		0.00	ns
t _{RCKH}	RCLK High		0.77		0.77		0.77	ns
t _{RCKL}	RCLK Low		0.93		0.93		0.93	ns
t _{RCKP}	Minimum RCLK period	1.70		1.70		1.70		ns
t _{CLRHF}	Clear High		0.00		0.00		0.00	ns
t _{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t _{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t _{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t _{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		1.32		1.51		1.77	ns
t _{RCK2RD2}	RCLK-To-OUT (Non-Pipelined)		2.16		2.46		2.90	ns

Note: Timing data for this single block FIFO has a depth of 4,096. For all other combinations, use Microsemi's timing software.

Table 2-99 • Two FIFO Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
FIFO Module Timing								
t _{WSU}	Write Setup		13.75		15.66		18.41	ns
t _{WHD}	Write Hold		0.00		0.00		0.00	ns
t _{WCKH}	WCLK High		0.75		0.75		0.75	ns
t _{WCKL}	WCLK Low		1.76		1.76		1.76	ns
t _{WCKP}	Minimum WCLK Period	2.51		2.51		2.51		ns
t _{RSU}	Read Setup		14.33		16.32		19.19	ns
t _{RHD}	Read Hold		0.00		0.00		0.00	ns
t _{RCKH}	RCLK High		0.73		0.73		0.73	ns
t _{RCKL}	RCLK Low		1.89		1.89		1.89	ns
t _{RCKP}	Minimum RCLK period	2.62		2.62		2.62		ns
t _{CLRHF}	Clear High		0.00		0.00		0.00	ns
t _{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t _{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t _{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t _{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
t _{RCK2RD2}	RCLK-To-OUT (Nonpipelined)		2.26		2.58		3.03	ns

Note: Timing data for these two cascaded FIFO blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

FG676	
AX1000 Function	Pin Number
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

FG676	
AX1000 Function	Pin Number
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

FG676	
AX1000 Function	Pin Number
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG676	
AX1000 Function	Pin Number
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	Pin Number
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	Pin Number
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896		FG896		FG896	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
NC	K1	VCCA	N20	VCCDA	AF19
NC	K2	VCCA	P11	VCCDA	C13
NC	L30	VCCA	P20	VCCDA	C5
NC	M30	VCCA	R11	VCCDA	D13
NC	N29	VCCA	R20	VCCDA	D19
NC	T1	VCCA	T11	VCCDA	D3
NC	U1	VCCA	T20	VCCDA	E18
NC	W30	VCCA	U11	VCCDA	F26
NC	Y1	VCCA	U20	VCCDA	G16
NC	Y2	VCCA	V11	VCCDA	T25
NC	Y30	VCCA	V20	VCCDA	T4
PRA	G15	VCCA	W11	VCCIB0	A3
PRB	D16	VCCA	W20	VCCIB0	B3
PRC	AB16	VCCA	Y12	VCCIB0	J10
PRD	AF16	VCCA	Y13	VCCIB0	J11
TCK	G7	VCCA	Y14	VCCIB0	J12
TDI	D5	VCCA	Y15	VCCIB0	K11
TDO	J8	VCCA	Y16	VCCIB0	K12
TMS	F6	VCCA	Y17	VCCIB0	K13
TRST	C4	VCCA	Y18	VCCIB0	K14
VCCA	AD6	VCCA	Y19	VCCIB0	K15
VCCA	AH26	VCCPLA	G14	VCCIB1	A28
VCCA	E28	VCCPLB	H15	VCCIB1	B28
VCCA	E3	VCCPLC	G17	VCCIB1	J19
VCCA	L12	VCCPLD	J16	VCCIB1	J20
VCCA	L13	VCCPLE	AH17	VCCIB1	J21
VCCA	L14	VCCPLF	AC16	VCCIB1	K16
VCCA	L15	VCCPLG	AH14	VCCIB1	K17
VCCA	L16	VCCPLH	AD15	VCCIB1	K18
VCCA	L17	VCCDA	AD24	VCCIB1	K19
VCCA	L18	VCCDA	AD7	VCCIB1	K20
VCCA	L19	VCCDA	AF12	VCCIB2	C29
VCCA	M11	VCCDA	AF13	VCCIB2	C30
VCCA	M20	VCCDA	AF15	VCCIB2	K22
VCCA	N11	VCCDA	AF18	VCCIB2	L21

FG896	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	B4
IO00PB0F0	A4
IO01NB0F0	F8
IO01PB0F0	F7
IO02NB0F0	D6
IO02PB0F0	E6
IO04NB0F0	A5
IO04PB0F0	B5
IO05NB0F0	H8
IO05PB0F0	G8
IO06NB0F0	D7
IO06PB0F0	E7
IO07NB0F0	D8
IO07PB0F0	E8
IO08NB0F0	C7
IO08PB0F0	C6
IO09NB0F0	G9
IO09PB0F0	H9
IO10NB0F0	A6
IO10PB0F0	B6
IO11NB0F0	H10
IO11PB0F0	G10
IO12NB0F1	E9
IO12PB0F1	F9
IO13NB0F1	E10
IO13PB0F1	F10
IO15NB0F1	F11
IO15PB0F1	G11
IO16NB0F1	A7
IO16PB0F1	B7
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	C9
IO18PB0F1	C8

FG896	
AX2000 Function	Pin Number
IO19NB0F1	D11
IO19PB0F1	E11
IO20PB0F1	B8
IO21NB0F1	H12
IO21PB0F1	H11
IO23NB0F2	A10
IO23PB0F2	A9
IO25NB0F2	F12
IO25PB0F2	G12
IO26NB0F2	B11
IO26PB0F2	B10
IO27NB0F2	D12
IO27PB0F2	E12
IO28NB0F2	C12
IO28PB0F2	C11
IO30NB0F2	A12
IO30PB0F2	A11
IO31NB0F2	F13
IO31PB0F2	G13
IO33NB0F2	H13
IO33PB0F2	J13
IO34NB0F3	B13
IO34PB0F3	B12
IO37NB0F3	E14
IO37PB0F3	E13
IO38NB0F3	B14
IO38PB0F3	A14
IO39NB0F3	H14
IO39PB0F3	J14
IO40NB0F3	B15
IO40PB0F3	A15
IO41NB0F3/HCLKAN	C14
IO41PB0F3/HCLKAP	D14
IO42NB0F3/HCLKBN	E15
IO42PB0F3/HCLKBP	D15

FG896	
AX2000 Function	Pin Number
Bank 1	
IO43NB1F4/HCLKCN	E17
IO43PB1F4/HCLKCP	E16
IO44NB1F4/HCLKDN	C17
IO44PB1F4/HCLKDP	D17
IO45NB1F4	A16
IO45PB1F4	B16
IO47NB1F4	H17
IO47PB1F4	J17
IO48NB1F4	A17
IO48PB1F4	B17
IO49NB1F4	H18
IO49PB1F4	J18
IO51NB1F4	F18
IO51PB1F4	G18
IO52NB1F4	B18
IO53NB1F4	D18
IO53PB1F4	C18
IO55NB1F5	H19
IO55PB1F5	G19
IO56NB1F5	B19
IO56PB1F5	A19
IO57NB1F5	E20
IO57PB1F5	E19
IO58NB1F5	C20
IO58PB1F5	C19
IO59NB1F5	B20
IO59PB1F5	A20
IO61NB1F5	F20
IO61PB1F5	F19
IO62NB1F5	A22
IO62PB1F5	A21
IO63NB1F5	D21
IO63PB1F5	D20
IO65NB1F6	G20

CQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

CQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

CQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CG624		CG624		CG624	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO131NB4F12	V19	IO153NB4F14	Y15	IO173PB5F16	Y11
IO131PB4F12	W19	IO153PB4F14	Y16	IO174NB5F16	AB10
IO133NB4F12	Y18	IO155NB4F14	V15	IO174PB5F16	AB11
IO133PB4F12	Y19	IO155PB4F14	V16	IO175NB5F16	AC9
IO135NB4F12	W18	IO156NB4F14	AB14	IO175PB5F16	AE9
IO135PB4F12	V18	IO156PB4F14	AB15	IO177NB5F16	AA8
IO137NB4F12	Y17	IO157NB4F14	AE14	IO177PB5F16	Y8
IO137PB4F12	AA17	IO157PB4F14	AC18	IO178NB5F16	Y6
IO138NB4F12	AB19	IO158NB4F14	AC15	IO178PB5F16	W6
IO138PB4F12	AB18	IO158PB4F14	AC19	IO179NB5F16	Y10
IO139NB4F13	AA19	IO159NB4F14/CLKEN	W14	IO179PB5F16	W10
IO139PB4F13	U18	IO159PB4F14/CLKEP	W15	IO180NB5F16	Y7
IO140NB4F13	AC20	IO160NB4F14/CLKFN	AC13	IO180PB5F16	W7
IO140PB4F13	AC21	IO160PB4F14/CLKFP	AD13	IO181NB5F17	AD9
IO141NB4F13	AD17	Bank 5		IO181PB5F17	AD10
IO141PB4F13	AD18	IO161NB5F15/CLKGN	W13	IO182NB5F17	AE10
IO142NB4F13	AD21	IO161PB5F15/CLKGP	Y13	IO182PB5F17	AE11
IO142PB4F13	AD22	IO162NB5F15/CLKHN	AC12	IO183NB5F17	AD7
IO143NB4F13	AB17	IO162PB5F15/CLKHP	AD12	IO183PB5F17	AD8
IO143PB4F13	AC17	IO163NB5F15	V9	IO184NB5F17	AB9
IO144PB4F13	AE22	IO163PB5F15	V10	IO185NB5F17	AE6
IO145NB4F13	AE15	IO164NB5F15	V11	IO185PB5F17	AE7
IO145PB4F13	AE16	IO164PB5F15	T13	IO186NB5F17	AE4
IO146NB4F13	AD19	IO165NB5F15	U13	IO186PB5F17	AE5
IO146PB4F13	AD20	IO165PB5F15	V13	IO187NB5F17	AA9
IO147NB4F13	AD15	IO167NB5F15	W11	IO187PB5F17	Y9
IO147PB4F13	AD16	IO167PB5F15	W12	IO188NB5F17	U8
IO148PB4F13	AE21	IO168NB5F15	AB6	IO189NB5F17	AD5
IO149NB4F13	AD14	IO168PB5F15	AA6	IO189PB5F17	AD6
IO149PB4F13	AC14	IO169NB5F15	V8	IO191NB5F17	AC5
IO150NB4F13	AE19	IO169PB5F15	V7	IO191PB5F17	AC6
IO150PB4F13	AE20	IO171NB5F16	W8	IO192NB5F17	AB7
IO151NB4F13	V17	IO171PB5F16	W9	IO192PB5F17	AC7
IO151PB4F13	W17	IO172NB5F16	AB8	Bank 6	
IO152NB4F14	AB16	IO172PB5F16	AC8	IO193NB6F18	U6
IO152PB4F14	W16	IO173NB5F16	AA11	IO193PB6F18	U5

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84